		SPECIF	FICATIONS	
CUSTO	MER			
SAMPL	E CODE (Ver.)		•	
MASS D	DODUCTION CODE	(Von)	PC2004WRF-A	AWB-B-Q(Ver.B)
	MASS PRODUCTION CODE (Ver.) : DRAWING NO. (Ver.)		HLMD-PC200	4WRF-AWB-B-Q (Ver.001)
		C 4	er Approved	
				l l
			Da	te:
	Approved	QC (<u>Da</u> Confirmed	te: Designer
	Approved 蔡志傳			
	_		Confirmed	Designer
* T	蔡志傳 proval For Specifications Only. his specification is subject to ch	ange without not	S 京 本 体 ice.	Besigner 楊清龍
* T)	蔡志傳 proval For Specifications Only. his specification is subject to ch	ange without not	S 京 本 体 ice.	Besigner 楊清龍
* T)	蔡志傳 proval For Specifications Only. his specification is subject to ch	ange without not	S 京 本 体 ice.	Besigner 楊清龍
* T P M App	蔡志傳 Proval For Specifications Only. This specification is subject to che Please contact Powertip or it's reproval For Specifications and Security Specifications Spec	nange without not epresentative before ample.	S 京 本 体 ice.	Based on this specification.
* T)	蔡志傳 proval For Specifications Only. his specification is subject to che Please contact Powertip or it's re- proval For Specifications and Sa	nange without not epresentative before ample.	Example 1 Example 1	Basigner 楊清龍 based on this specification.

(#081160)

NO.PT-A-005-6



RECORDS OF REVISION

Date	Rev.	Description	Note	Page
2006/01/10	0	PC2004WRF-AWB-B-Qis the ROHS compliant part number based on Powertip's standard PC2004WRF-AWB-B		
2007/10/7	A	Update Timing Characteristics and Display Command		13,15
2009/10/07	В	Update LCM Drawing		8

Total: 22 Page



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- 1.2 Mechanical Specifications
- 1.3 Absolute Maximum Ratings
- 1.4 DC Electrical Characteristics
- 1.5 Optical Characteristics
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- 2.2 Interface Pin Description
- 2.3 Timing Characteristics
- 2.4 Display Command
- 2.5 Character Pattern

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- 5.1 Safety
- 5.2 Handling
- 5.3 Storage
- **5.4** Terms of Warranty

6. THIS PRODUCT CONFORMS THE ROHS OF PTC.

Note: For detailed information please refer to IC data sheet: ST7066U



1. SPECIFICATIONS

1.1 Features

Item	Standard Value
Display Type	20 *4 Characters
LCD Type	FSTN, White Transflective, Positive, Normal Temp.
Driver Condition	LCD Module 1/16 Duty, 1/5Bias
Viewing Direction	6 O'clock
Backlight	white LED B/L
Weight	70.0g
Interface	_
Other	

1.2 Mechanical Specifications

Item	Standard Value	Unit
Outline Dimension	98.0 (L) * 60.0 (w) *13.3 (H)(Max)	mm
Viewing Area	76.0 (L) * 25.2 (w)	mm
Active Area	70.4 (L) *20.8 (w)	mm
Dot Size	0.55 (L) * 0.55 (w)	mm
Dot Pitch	0.60(L) * 0.60(w)	mm

Note: For detailed information please refer to LCM drawing

1.3 Absolute Maximum Ratings

	- 8 ~				
Item	Symbol	Condition	Min.	Max.	Unit
Power Supply Voltage	V_{DD}	_	-0.3	7.0	V
LCD Driver Supply Voltage	V_{LCD}	_	V _{DD} -10.0	V _{DD} +0.3	V
Input Voltage	V _{IN}	_	-0.3	V _{DD} +0.3	V
Operating Temperature	T_{OP}	Excluded B/L	0	50	$^{\circ}\!\mathbb{C}$
Storage Temperature	T_{ST}	Excluded B/L	-20	70	$^{\circ}\!\mathbb{C}$
Storage Humidity	H_D	Ta < 40 °C	-	90	%RH



1.4 DC Electrical Characteristics

 $V_{DD}\!=5.0\pm0.5V$, $V_{SS}\!=\!0V$, $Ta=25^{\circ}\!\text{C}$

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Logic Supply Voltage	V_{DD}	_	4.5	5.0	5.5	V
"H" Input Voltage	V_{IH}	_	$0.7V_{DD}$	-	V_{DD}	V
"L" Input Voltage	V_{IL}	_	-0.3	-	0.6	V
"H" Output Voltage	V_{OH}	IOH=-0.1mA	3.9	-	V_{DD}	V
"L" Output Voltage	V_{OL}	IOL=0.1mA	-	-	0.4	V
Supply Current	I_{DD}	$V_{DD} = 5.0 \text{ V}$		1.5	2.0	mA
		0°C				
LCM Driver Voltage	V_{OP}	25°C *1	4.4	4.6	4.8	V
		50°C				

Note: *1. THE V_{OP} TEST POINT IS V_{DD} - V_{O}

1.5 Optical Characteristics

LCD Panel 1/16Duty , 1/4Bias , $V_{LCD} = 4.6V$, $T_a = 25^{\circ}C$

Item	Symbol	Conditions	Min.	Тур.	Max.	Reference
View Angle	θ	C≥2.0,Ø= 0°	0	-	40°	Notes 1 & 2
Contrast Ratio	С	θ=5°, Ø= 0°	6	8	-	Note 3
Response Time(rise)	tr	θ = 5°, \varnothing = 0°	-	70 ms	105 ms	Note 4
Response Time(fall)	tf	θ = 5°, \varnothing = 0°	-	150ms	225 ms	Note 4



Note 1: Definition of angles θ and \emptyset

Light (when reflected) $z (\theta=0^{\circ})$

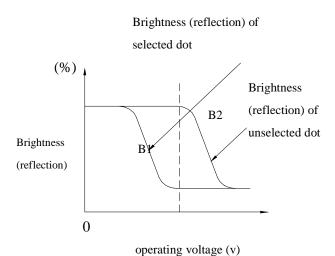
Sensor θ $Y'(\emptyset=180^{\circ})$ X' Z' $X(\emptyset=90^{\circ})$

Light (when transmitted) $Y(\varnothing=0^{\circ})$ $(\theta=90^{\circ})$

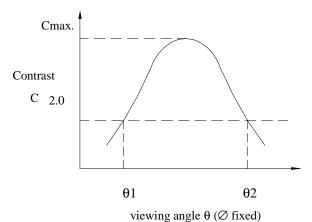
Note 3: Definition of contrast C

Brightness (reflection) of unselected dot (B2)

Brightness (reflection) of selected dot (B1)

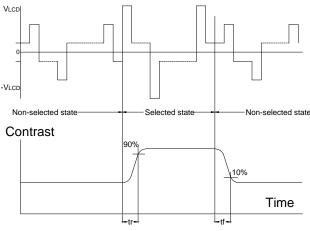


Note 2: Definition of viewing angles $\theta 1$ and $\theta 2$



Note: Optimum viewing angle with the naked eye and viewing angle θ at Cmax. Above are not always the same

Note 4: Definition of response time



Note: Measured with a transmissive LCD panel which is displayed 1 cm²

 V_{LCD} : Operating voltage f_{FRM} : Frame frequency t_r : Response time (rise) t_f : Response time (fall)



1.6 Backlight Characteristics

LCD Module with LED Backlight

Maximum Ratings

Item	Symbol	Conditions	Min.	Max.	Unit
Forward Current	IF	Ta =25°℃	-	72	mA
Reverse Voltage	VR	Ta =25°℃	-	5	V
Power Dissipation	PO	Ta =25°C	-	0.29	W

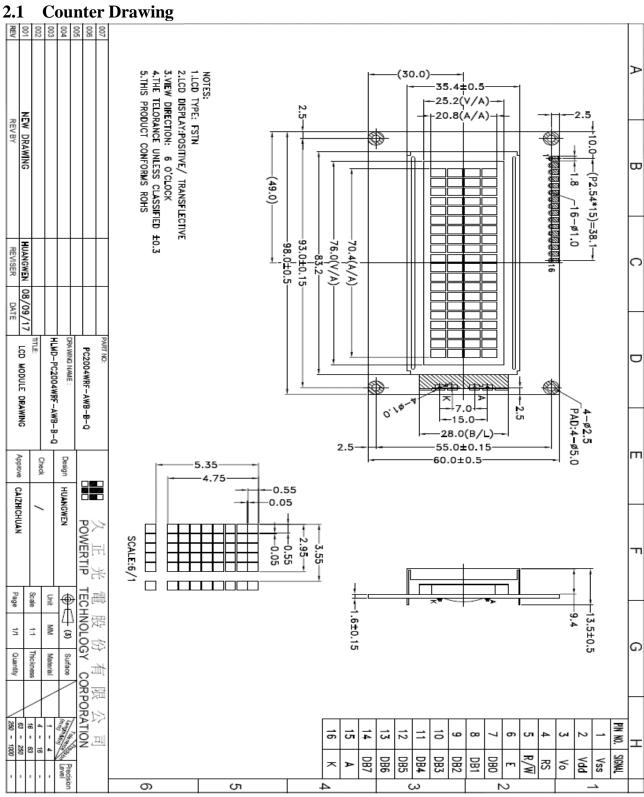
Electrical / Optical Characteristics

Ta =25°C

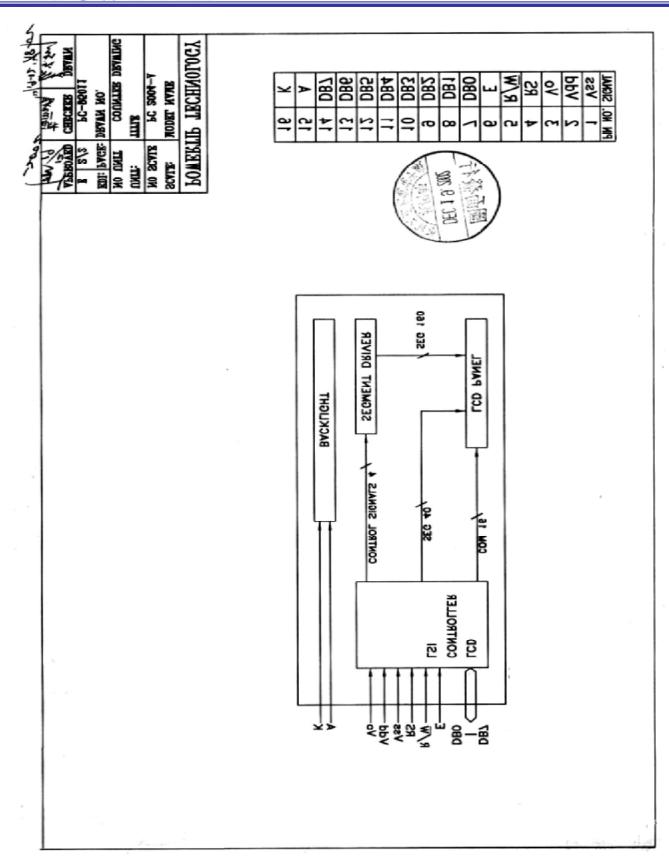
Item	Symbol	Conditions	Min.	Тур.	Max.	Unit
Forward Voltage	VF	IF= 60 mA	3.0	3.3	4.0	V
Reverse Current	IR	VR= 5 V	-	-	0.15	mA
Luminous Intensity (Without LCD)	IV	IF= 60 mA	185	290	-	cd/m ²
Wavelength	X	IF= 60 mA	0.26	0.29	0.32	nm
wavelength	у	IF- 00 IIIA	0.27	0.30	0.33	nm
Color			White			



2. MODULE STRUCTURE





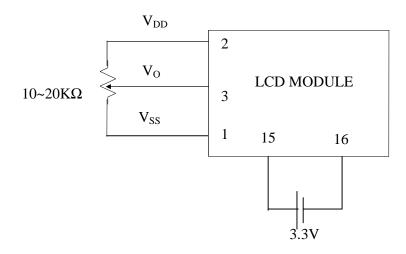




2.2 Interface Pin Description

Pin No.	Symbol	Signal Description
1	Vss	Power Supply (V _{SS} =0)
2	Vdd	Power Supply (V _{DD} >V _{SS})
3	Vo	Operating voltage for LCD (variable)
		Register Selection input
4	RS	High = Data register
4	KS	Low = Instruction register (for write)
		Busy flag address counter (for read)
		Read/Write signal input is used to select the read/write
5	R/\overline{W}	mode.
		High = Read mode, Low = Write mode
6	E	Start enable signal to read or write the data
		Four low order bi-directional three-state data bus lines.
7~10	DB0 ~ DB3	Used for data transfer between the MPU and the LCD
/~10	DB0 ~ DB3	module.
		These four are not used during 4-bit operation.
		Four high order bi-directional three-state data bus lines.
11~14	DB4 ~ DB7	Used for data transfer between the MPU and the LCD
		module.
		DB7 can be used as a busy flag.
15	A	Power supply for LED B / L (+)
16	K	Power supply for LED B / L (-)

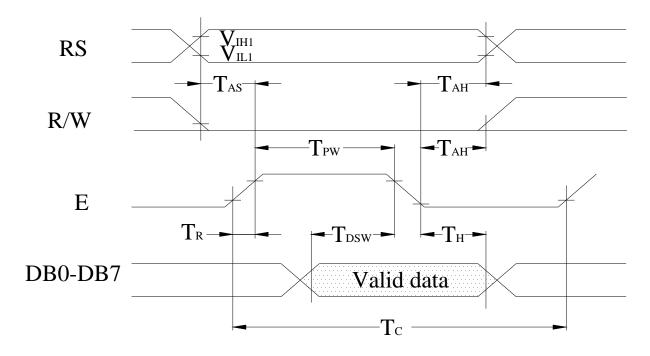
Contrast Adjust



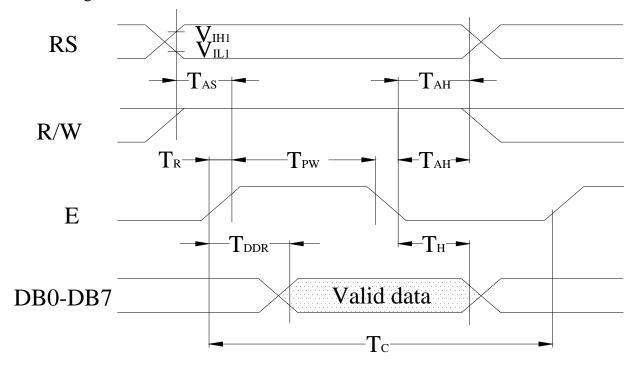


2.3 Timing Characteristics

• Writing data from MPU to ST7066U



I Reading data from ST7066U to MPU





• Write Mode (Writing data from MPU to ST7066U)

 $(VDD = +5V, Ta = 25^{\circ}C)$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
$T_{\rm C}$	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T_{AH}	Address Hold Time	Pins :RS,RW,E	10	-	-	ns
T_{DSW}	Data Setup Time	Pins:DB0~DB7	40	1	-	ns
T_{H}	Data Hold Time	Pins:DB0~DB7	10	-	-	ns

• Read Mode (Reading data from ST7066U to MPU)

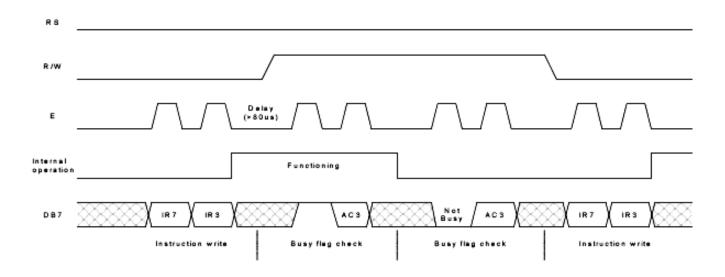
 $(VDD = +5V, Ta = 25^{\circ}C)$

Symbol	Characteristics	Test Condition	Min.	Тур.	Max.	Unit
$T_{\rm C}$	Enable Cycle Time	Pin E	1200	-	-	ns
T_{PW}	Enable Pulse Width	Pin E	140	-	-	ns
T_R, T_F	Enable Rise / Fall Time	Pin E	-	-	25	ns
T _{AS}	Address Setup Time	Pins: RS , RW,E	0	-	-	ns
T_{AH}	Address Hold Time	Pins :RS,RW,E	10	1	-	ns
T_{DDR}	Data Setup Time	Pins:DB0~DB7	-	-	100	ns
T_{H}	Data Hold Time	Pins:DB0~DB7	10	-	-	ns



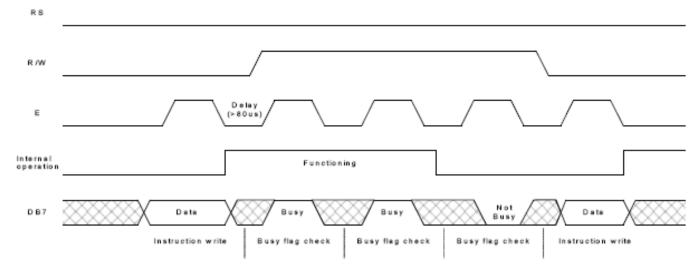
For 4-bit interface date, only four bus lines (DB4 to DB7) are used for transfer.

Example of busy flag check timing sequence



For 8-bit interface date, all eight bus lines (DB0 to DB7) are used .

Example of busy flag check timing sequence





2.4 Display Command

					Instru	iction	Code			Description			
Instructions	RS	R/W	DB 7	DB 6	DB 5	DB 4			DB DB		Description	Time (270KHz)	
Clear Display	0	0	0	0	0	0	0	0	0	1	Write "20H" to DDRAM. and set DDRAM address to "00H" from AC.	1.52ms	
Return Home	0	0	0	0	0	0	0	0	1	×	Set DDRAM address to "00H" from AC and return cursor to it's original position if shifted. The contents of DDRAM are not changed.	1.52ms	
Entry Mode Set	0	0	0	0	0	0	0	1	I/D	S	Sets cursor move direction and specifies display shift. These operations are performed during data write and read.	37118	
Display ON/OFF	0	0	0	0	0	0	1	D	С	В	D=1 : entire display on C=1 : cursor on B=1 : cursor position on	37µs	
Cursor or Display Shift	0	0	0	0	0	1	S/C	R/L	×	×	Set cursor moving and display shift control bit, and the direction, without changing of DDRAM data.	37µs	
Function Set	0	0	0	0	1	DL	N	F	×	×	DL: interface data is 8/4 bits NL: number of line is 2/1 F: font size is 5×11/5×8	37µs	
Set CGRAM Address	0	0	0	1	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Set CGRAM address in address counter.	37µs	
Set DDRAM Address	0	0	1	AC 6	AC 5	AC 4	AC 3	AC 2	AC 1	AC 0	Set DDRAM address in address counter.	37µs	



Read Busy Flag and Address	0	1	BF	AC 6	AC 5	AC 4	AC 3	AC 2	AC	AC 0	Whether during internal operation or not can be known by reading BF. The contents of address counter can also be read.	Oμs
Write Data	1	0	D7	D6	D5	D4	D3	D2	D1	D0	Write data into internal RAM	37µs
to RAM	-		υ,	В				22	Di	Do	(DDRAM/CGRAM).	υ, μυ
Read Data	1	1	D7	D6	D5	D4	D3	D2	D1	D0	Read data from internal RAM	37µs
from RAM	1	1	יע	טט	D5	D4	טט	D2	DI	טט	(DDRAM/CGRAM).	31μ8

Note:

Be sure the ST7066U is not in the busy state (BF=0) before sending an instruction from the MPU to the ST7066.

If an instruction is sent without checking the busy flag, the time between the first instruction and next instruction will take much longer than the instruction time itself.

Before checking BF, be sure to wait at least 80us.. Do not keep "E" always "High" for checking BF. Refer to Instruction Table for the list of each instruction execution time.



2.5 Character Pattern

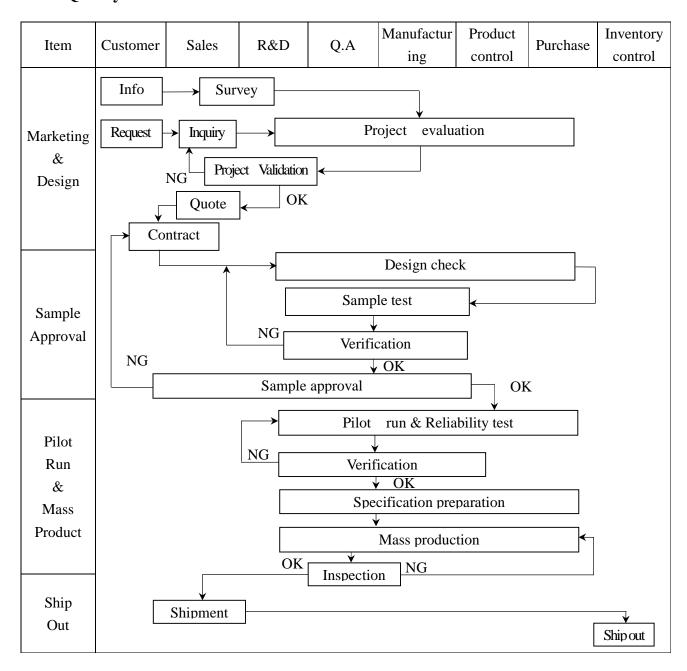
■ CHARACTER PATTERN(EB,WB)

			ligh	4-b	it (C)4to	D7	of (Cha	ract	er C	ode	(H	еха	deci	mal)
40		0	1	2	3	4	5	6	7	8	9	Α	В	С	D	E	F
	0	CG RAM (1)	<u></u>				 	==	!::: -			- =	-	1.			-::
S. J. W. W. Dy. A.	1	CG RAM (2)		1	1			-:::	-::::	I		=		!		•	I:
Walley Street	2	CG RAM (3)	۳.	==			F	<u> </u>	! -	#	H	=====	-:-	::::	===	:::	
2000 COLUMN	3	CG RAM (4)		##		! :	:::::	3	::::-	-#	:::::::::::::::::::::::::::::::::::::::	<u>-</u> -			41	===	4
THE RESIDENCE OF THE PARTY OF T	4	CG RAM (5)	1-	:	:: -		T		†	-===	====		••		1		
THE REAL PROPERTY AND ADDRESS OF THE PERSON NAMED IN COLUMN TWO PERSON NAMED IN COLUMN TRANSPORT NAMED IN COLUMN TWO PERSON NAMED IN COLUMN TRANSPORT NAMED IN COLUMN TWO PERSON NAMED IN COLUMN TRANSPORT NAMED IN COLUMN	5	CG RAM (6)	I.	::-: <u>:</u>		!	II	====	II	- 🔠	====	£	! ::	-1	::1	17	1
	6	CG RAM (7)			===		i.,.i		II	-===	 	4	! _{!-!}				!!!
AND WATER TO STREET	7	CG RAM (8)	!	:=			ĻĻİ	-==	1,.,1	===	<u>.</u>	F	<u>:-:</u> :		, [,] ,	1	==
ACT IN SECTION AND ADDRESS OF	8	CG RAM (1)		!		 i	: -:	i	;:::	#	<u>.</u>	.; *	:	- <u>:</u>	===	! =:	
	9	CG RAM (2)		<u>:</u> :	<u>'</u>	I	٠,.:	1	':::I	===			∹	I	Ш		-1:-
	A	CG RAM (3)	∷	:-[-:	==		===	.j	<u></u>				:-		:::	<u> </u>	
STATISTICS OF THE STATE OF	В	CG RAM (4)			#	k:	<u></u>	! ::	₹	1	:-:i		-::		-1-	1:	-:
CONTRACTOR DESCRIPTION OF THE PERSON OF THE	C	CG RAM (5)		:=	-::	! .	٠	1		i			:: -	i	#	===	
100 Meller 1000	D	CG RAM (6)	ı ⁻ ı,ı					[*·]	<u>.</u> ;-	1	-#		::: ::	==		H	*****
THE CASE OF TAKE A	E	CG RAM (7)		==		 - -		! ":		H			- !			 -	
	F	CG RAM (8)	⊞					::	.: <u>.</u> :.	Ä	<u>.:</u>	::::			<u> </u>		

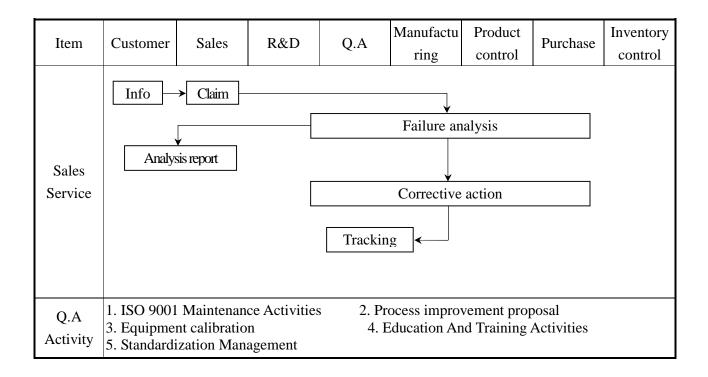


3. QUALITY ASSURANCE SYSTEM

3.1 Quality Assurance Flow Chart









3.2 Inspection Specification

Inspection Standard : MIL-STD-105E Table Normal Inspection Single Sampling Level $\ \ \, \square \ \, \circ$

Equipment: Gauge · MIL-STD · Powertip Tester · Sample ·

IQC Defect Level : Major Defect AQL 0.4; Minor Defect AQL 1.5 $\,{}^{\circ}$

FQC Defect Level: 100% Inspection • OUT Going Defect Level: Sampling •

Specification:

NO	Item	Specification	Judge	Level
1	Part Number	The part number is inconsistent with work order of production	N.G.	Major
2	Quantity	The quantity is inconsistent with work order of production	N.G.	Major
	Electronic	The display lacks of some patterns.	N.G.	Major
	characteristics of	Missing line.	N.G.	Major
3	LCM	The size of missing dot, A is $> 1/2$ Dot size	N.G.	Major
	$A=(L+W)\div 2$	There is no function.	N.G.	Major
		Output data is error	N.G.	Major
		Material is different with work order of production	N.G.	Major
		LCD is assembled in inverse direction	N.G.	Major
		Bezel is assembled in inverse direction	N.G.	Major
		Shadow is within LCD viewing area + 0.5 mm	N.G.	Major
	Appearance of	The diameter of dirty particle, A is > 0.4 mm	N.G.	Minor
	$\begin{array}{c} LCD \\ A=(L+W) \div 2 \end{array}$	Dirty particle length is > 3.0 mm, and 0.01 mm $<$ width ≤ 0.05 mm	N.G.	Minor
4	Dirty particle (Including scratch \ bubble)	Display is without protective film	N.G.	Minor
		Conductive rubber is over bezel 1mm	N.G.	Minor
		Polarizer exceeds over viewing area of LCD	N.G.	Minor
	scratch voubble)	Area of bubble in polarizer, $A > 1.0$ mm, the number of bubble is > 1 piece.	N.G.	Minor
		0.4mm $<$ Area of bubble in polarizer, A $<$ 1.0 mm, the number of bubble is $>$ 4 pieces.	N.G.	Minor
		Burned area or wrong part number is on PCB	N.G.	Major
		The symbol, character, and mark of PCB are unidentifiable.	N.G	Minor
		The stripped solder mask, A is > 1.0mm	N.G.	Minor
	Appearance of	0.3 mm $<$ stripped solder mask or visible circuit, A $<$ 1.0 mm, and the number is ≥ 4 pieces	N.G.	Minor
5	PCB	There is particle between the circuits in solder mask	N.G	Minor
	$A=(L+W)\div 2$	The circuit is peeled off or cracked	N.G	Minor
		There is any circuits risen or exposed.	N.G	Minor
		$0.2 \text{mm} < \text{Area of solder ball, A is } \leq 0.4 \text{mm}$ The number of solder ball is ≥ 3 pieces	N.G	Minor
		The magnitude of solder ball, A is ≥ 0.4 mm.	N.G	Minor



Item	Specification	Judge	Level
	The shape of modeling is deformed by touching.	N.G.	Major
Appearance of	, ,	N.G.	Minor
molding $A=(L+W)\div 2$	Excessive epoxy: Diameter of modeling is >20mm	N.G.	Minor
	<u> </u>	N.G.	Minor
		N.G.	Minor
Appearance of frame	The area of stripped electroplate in top-view of frame, A is > 1.0mm.	N.G.	Minor
$A=(L+W)\div 2$	Rust or crack is (Top view only)	N.G.	Minor
	The scratched width of frame is > 0.06 mm. (Top view only)	N.G.	Minor
Electrical	The color of backlight is nonconforming	N.G.	Major
	Backlight can't work normally.	N.G.	Major
		N.G.	Major
	The unsoldering area of pin for backlight, A is $> 1/2$ solder joint area.	N.G.	Minor
A=(L+W)=2	The height of solder pin for backlight is >2.0mm	N.G.	Minor
	The mark or polarity of component is unidentifiable.	N.G.	Minor
	The height between bottom of component and surface of the PCB is floating >0.7mm	N.G.	Minor
Assembly parts A=(L + W)÷2	D>1/4W W D D D Pad	N.G.	Minor
	End solder joint width, D' is >50% width of component termination or width of pad	N.G.	Minor
	Side overhang, D is >25% width of component termination.	N.G.	Minor
	Component is cracked, deformed, and burned, etc.	N.G.	Minor
	The polarity of component is placed in inverse direction.	N.G.	Minor
	Maximum fillet height of solder extends onto the component body or minimum fillet height is <0.5mm.	N.G.	Minor
	Appearance of molding A=(L+W)÷2 Appearance of frame A=(L+W)÷2 Electrical characteristic of backlight A=(L+W)÷2	Appearance of molding A=(L+W)+2 The shape of modeling is deformed by touching. Insufficient epoxy: Circuit or pad of IC is visible Excessive epoxy: Diameter of modeling is > 20mm or height is > 2.5mm The diameter of pinhole in modeling, A is > 0.2mm. The folding angle of frame must be > 45° +10° The area of stripped electroplate in top-view of frame, A is > 1.0mm. Rust or crack is (Top view only) The scratched width of frame is > 0.06mm. (Top view only) The LED lamp can't work normally. The height of solder pin for backlight is > 2.0mm The mark or polarity of component is unidentifiable. The height between bottom of component and surface of the PCB is floating > 0.7mm D> 1/4W W D Assembly parts A=(L+W)+2 A=(L+W)+2 Assembly parts A=(L+W)+2 Asse	Appearance of molding A=(L+W)÷2 Appearance of molding A=(L+W)÷2 Appearance of frame A=(L+W)÷2 Appearance of frame A=(L+W)÷2 Electrical characteristic of backlight A=(L+W)÷2 Assembly parts A=(L+W)



4. RELIABILITY TEST

4.1 Reliability Test Condition

NO	Item	Test Condition						
1	High Temperature	Storage at 70 ±2°C 96~100 hrs Surrounding temperature, then storage at normal condition						
1	Storage	4hrs						
	I T	Storage at -20 $\pm 2^{\circ}$ C 96~100 hrs						
2	Low Temperature Storage	Surrounding temperature, then storage at normal condition 4hrs						
		1.Storage 96~100 hrs 60±2°C, 90~	95%RH surrounding					
		temperature, then storage at norm	mal condition 4hrs.					
3	High Temperature	(Excluding the polarizer).						
3	/Humidity Storage	or						
		2.Storage 96~100 hrs 40±2°C, 90~95%RH surrounding						
		temperature, then storage at normal condition 4 hrs.						
		$-20^{\circ}\text{C} \rightarrow 25^{\circ}\text{C} \rightarrow 70^{\circ}\text{C} \rightarrow 25^{\circ}\text{C}$						
4	Temperature Cycling	(30mins) (5mins) (30mins) (5mins)						
		10 Cycle						
_		10~55Hz (1 minute) 1.5mm						
5	Vibration	X,Y and Z direction * (each 2hrs)						
		Air Discharge:	Contact Discharge:					
		Apply 6 KV with 5 times	Apply 250V with 5 times					
		discharge for each polarity +/-	discharge for each polarity +/-					
6	ESD Test	T	Testing location:					
		Testing location:	1.Apply to bezel.					
		Around the face of LCD	2.Apply to Vdd, Vss.					
		Packing Weight (Kg)	Drop Height (cm)					
		0 ~ 45.4	122					
7	Drop Test	45.4 ~ 90.8	76					
		90.8 ~ 454	61					
		Over 454	46					



5. PRECAUTION RELATING PRODUCT HANDLING 5.1 SAFETY

- 5.1.1 If the LCD panel breaks, be careful not to get the liquid crystal to touch your skin.
- 5.1.2 If the liquid crystal touches your skin or clothes, please wash it off immediately by using soap and water.

5.2 HANDLING

- 5.2.1 Avoid any strong mechanical shock which can break the glass.
- 5.2.2 Avoid static electricity which can damage the CMOS LSI—When working with the module, be sure to ground your body and any electrical equipment you may be using.
- 5.2.3 Do not remove the panel or frame from the module.
- 5.2.4 The polarizing plate of the display is very fragile. So, please handle it very carefully, do not touch, push or rub the exposed polarizing with anything harder than an HB pencil lead (glass, tweezers, etc.)
- 5.2.5 Do not wipe the polarizing plate with a dry cloth, as it may easily scratch the surface of plate.
- 5.2.6 Do not touch the display area with bare hands, this will stain the display area.
- 5.2.7 Do not use ketonics solvent & aromatic solvent. Use with a soft cloth soaked with a cleaning naphtha solvent.
- 5.2.8 To control temperature and time of soldering is $350\pm20^{\circ}$ C and 3-5 sec.
- 5.2.9 To avoid liquid (include organic solvent) stained on LCM.

5.3 STORAGE

- 5.3.1 Store the panel or module in a dark place where the temperature is 25° C $\pm 5^{\circ}$ C and the humidity is below 65% RH.
- 5.3.2 Do not place the module near organics solvents or corrosive gases.
- 5.3.3 Do not crush, shake, or jolt the module.

5.4 TERMS OF WARRANTY

5.4.1 Applicable warrant period

The period is within thirteen months since the date of shipping out under normal using and storage conditions.

5.4.2 Unaccepted responsibility

This product has been manufactured to your company's specification as a part for use in your company's general electronic products. It is guaranteed to perform according to delivery specifications. For any other use apart from general electronic equipment, we cannot take responsibility if the product is used in nuclear power control equipment, aerospace equipment, fire and security systems or any other applications in which there is a direct risk to human life and where extremely high levels of reliability are required.